

m/c Configuration

2200 EVO 950-2218-2048

	Base price in EUR	actual configuration		
11	Software version	Tbd		
12	Operation system	Tbd		
13	Condition	Used		
	Main System			
20	Bondhead	Standard		
21	Time-pressure dispenser	No		
22	Volumetric dispenser	No		
23	Musashi dispenser	No		
24	Substrate camera	Yes		
25	Toolbank	7 positions		
26	Squeegee unit	Yes		
27	Flipchip unit	No		
28	Fluxslider	No		
29	Wafertable	Up to 12" wafer		
30	Wafer magazine lift	No		
31	Wafercamera	Yes		
32*	Ejector system	Yes		
33	Ejector carousel	No		
34	Uplooking camera	Yes		
35	Static wafflepack holder	TBD		
	ID System			
40	Bondhead	No		
41	Time-pressure dispenser	No		
42	Volumetric dispenser	No		
43	Musashi dispenser	No		
44	Substrate camera	No		
45	Squeegee unit	No		
	Transport system			
50*	Inputbuffer	No		
51*	Outputbuffer	No		
52*	Input magazine handler	No		
53*	Output magazine handler	No		
	Customized options			
60	P-Parts	No		
61	Heated P-Part	No		
62*	Process related tools	No		

63	Calibration tools	No		
64	Support for upgrade	No		
65	Installation	No		
66	Laser marker	No		
67	Internal UV-curing	No		
68	UV post curing	No		

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Upgrade to customers spec	Comments
close to APM+	
Right of bondhead	
front mount squeegee 113030	
300mm wafer table	Grip ring adapter 6" photo 151222
Zoko	
	113118 single ejector
	113045 blowoff box, uplooking camera, Squeegee
with front mount squeegee stamping	
NUTEK HANDLERS available	
NUTEK HANDLERS available	
	LED assembly with transformer 113009
